



FEATURES

I Ideal For Automated Placement

Glass Passivated Chip Junction

High Forward Surge Capability

Meets MSL Level1,per J-STD-020





MECHANICAL DATA

Case Material: Molded Plastic. UL Flammability
Classification Rating 94V-0
Moisture Sensitivity: Level 1 per J-STD-020
Polarity: Cathode line denotes the cathode end

APPROVALS Schematic Symbol

	Compliance with 2011/65/EU			
HF	Compliance with IEC61249-2-21:2003			

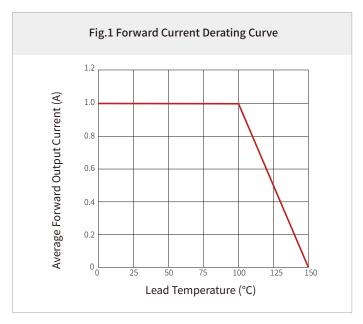
MAXIMUM RATINGS AND CHARACTERISTICS ($T_A = 25$ °C)

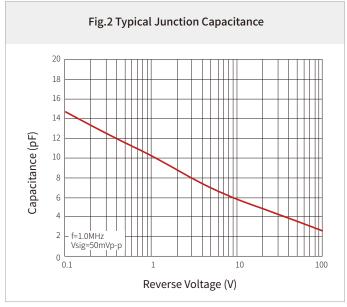
Parameter		Symbol	GS1004FL	GS1006FL	GS1010FL	Unit	
Marking			A4	A5	A7		
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	400	600	1000		
Maximum RMS Voltage		V_{RMS}	280	420	700	V	
Maximum DC Blocking Voltage		V_{DC}	400	600	1000		
Maximum Average Forward Re	ctified Current	I _{F(AV)}	1			٨	
Surge(Non-Repetitive)Forward Current@60Hz Half-Sine Wave,1 Cycle,Ta=25°C		I _{FSM}	30		- A		
Typical Junction Capacitance(Note 2)		CJ	7		pF		
Maximum Instantaneous Forward Voltage Drop Per Diode@1A ^(Note 1)		$V_{\rm F}$	1.1		V		
Maximum Reverse Current @Rated V _R	T _J =25°C	I _R			1		μA
	T _J =125°C			50		μΑ	
Typical Thermal Resistance		$R_{\theta J-A}$	85		°C/W		
Typical Thermal Resistance		$R_{\theta J-L}$	25				
Operating Junction Temperature Rang		T _J	-55~+150		°C		
Storage Temperature Rang		T_{STG}	-55~+150				

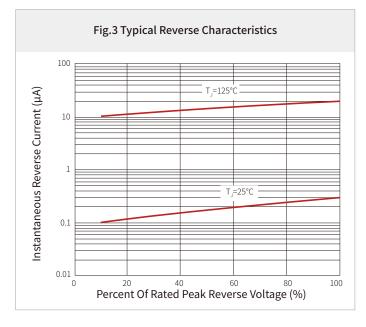
Note 1: Pulse Test With Pw=0.3ms Note 2: Pulse Test With Pw=30ms

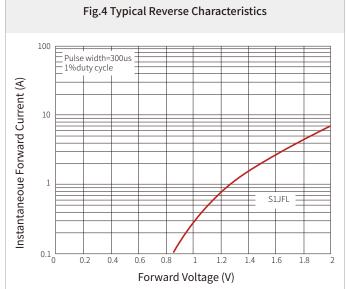


CHARACTERISTIC CURVES





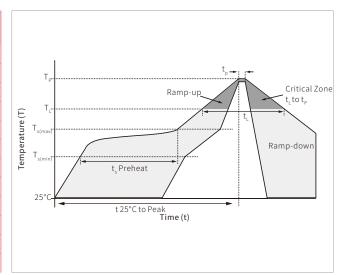




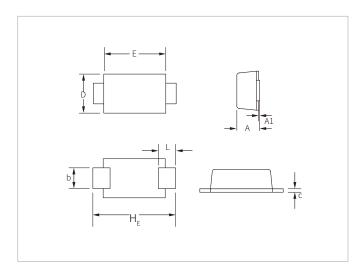


SOLDERING PARAMETERS

	Lead-free assembly		
	Temperature Max (T _{s(min)})	150°C	
Pre Heat	Temperature Max (T _{s(max)})	200°C	
	Time (min to max) (t_s)	60 – 180 secs	
Average ran	Average ramp up rate (Liquidus Temp (T _L) to peak		
	3°C/second max		
Reflow	Temperature (T _L) (Liquidus)	217°C	
	Time (min to max) (t_L)	60 – 150 seconds	
Peak Temp	260°C		
Time within	20 – 40 seconds		
Ramp-dow	6°C/second max		
Time 25°C t	8 minutes max.		
Do not exce	260°C		



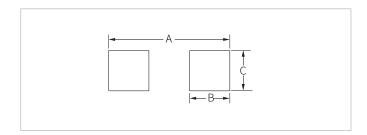
SOD-123FL PACKAGE INFORMATION



Ref.	Millim	neters	Inches		
	Min.	Max.	Min.	Max.	
А	0.95	1.45	0.037	0.057	
A1	0.00	0.10	0.000	0.004	
b	0.70	1.20	0.028	0.047	
С	0.05	0.30	0.002	0.012	
D	1.50	2.00	0.059	0.079	
Е	2.50	3.10	0.098	0.122	
L	0.35	0.90	0.014	0.035	
H _E	3.40	3.90	0.134	0.154	



RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
А	4.20	0.165
В	1.50	0.059
С	1.20	0.047

ORDERING INFORMATION

Pa	rt Number	Component Package	QTY/Reel	Reel Size
GS100	04FL-GS1010FL	SOD-123FL	3000PCS	7"



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Machai

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